

**OMNIMATE-data - RJ45-uttag omvandlare
RJ45M R1V 3.3N4Y/G TY****Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 16

D-32758 Detmold

Germany

Fon: +49 5231 14-0

Fax: +49 5231 14-292083

www.weidmueller.com



RJ45-sändarlansor (magnetiska) för gigabit-ändamål (1000 base-T) med integrerad kompenserad motverkar aktivt induktiva och kapacitiva kopplingar och gör att utrymme kan sparas på kretskortet.

- Lödningsprocess THT eller THR
- Brett utbud av olika design typer, även med inbyggda lysdioder och skärmade kontaktflikar
- Förpackad antingen på bricka (TY) eller antistatiskt på tape-on-reel (RL)
- Utvidgat temperaturområde, -40 °C till +85 °C
- Förstärkt guldager för förbättrat korrosionsskydd
- Överföringshastighet upp till 1 Gbit/sek

Allmänna beställningsdata

Typ	RJ45M R1V 3.3N4Y/G TY
Art.nr.	2461070000
Artikelbeteckning	Kretskortsstickanslutning, RJ45-uttag omvandlare, 10/100 MBit/s , THT/THR lödanslutning, 180°, Skärmflikar: ingen, 30-80 µm Ni / 30- µm Au , LED: Ja, gul, grön, Antal poler: 8, Bricka (manuell montering)
GTIN (EAN)	4050118476071
Frp	120 Stück
Förpackning	Bricka (manuell montering)

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Tekniska data**Mått och vikter**

Bredd	16 mm	Byggbredd (tum)	0,63 inch
Höjd	20,3 mm	Bygghöjd (tum)	0,799 inch
Höjd lägstbyggande	17 mm	Djup	16,8 mm
Byggdjup (tum)	0,661 inch	Nettovikt	3,658 g

Temperaturer

Driftstemperatur, max	85 °C	Driftstemperatur, min.	-40 °C
Lagertemperatur, max.	85 °C	Lagertemperatur, min.	-40 °C

Environmental Product Compliance

REACH SVHC	Lead 7439-92-1
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Systemparametrar

Anslutningstyp	Hylsa	Anslutningsvinkel	180°
Antal lödstift per pol	1	Antal poler	8
Avskärmning	Ja	Delning i mm (P)	1,27 mm
Delning i tum (P)	0,05 inch	Diameter bestyckningshål (D)	0,9 mm
Färg på höger LED	grön	Färg på vänster LED	gul
LED	Ja	Montering på kretskortet	THT/THR lödanslutning
Produktfamilj	OMNIMATE-data - RJ45-uttag omvandlare	Skärmmaterial	Mässing
Skyddsklass	IP20	Skärmarea	förnicklad
Skärmflikar	ingen	Stickcykler	750
Tolerans diameter bestyckningshål (D)	± 0,1 mm	Överföringshastighet	10/100 MBit/s

Elektriska egenskaper

Isolationshållfasthet	> 500 MΩ	Märkström	1,5 A
Märkspänning	125 V AC	Spänningstålighet kontakt/kontakt	1000 V DC
Spänningstålighet kontakt/skärm	1 500 V DC		

Packaging

Förpackning	Bricka (manuell montering)	VPE-längd	0 m
VPE-bredd	0 m	VPE-höjd	0 m

Materialdata

Isoleringsmaterial	PA 9T	Färgkod	svart
Färgtabell (jämförbar)	RAL 9011	Isoleringsmaterialgrupp	II
CTI	≥ 500	Isolationshållfasthet	> 500 MΩ
Moisture Level (MSL)	1	Brännbarhetsklass enligt UL 94	V-0
Kontaktgrundmaterial	Fosforbrons	Kontakttyta	Guld över nickel
Skiktstruktur för stiftkontakten	30-80 μ" Ni / 30- μ" Au	Lagertemperatur, min.	-40 °C
Lagertemperatur, max.	85 °C	Driftstemperatur, min.	-40 °C
Driftstemperatur, max	85 °C		

Klassificeringar

ETIM 6.0	EC002637	eClass 6.2	27-25-05-04
eClass 9.0	27-44-04-02	eClass 9.1	27-44-04-02

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Tekniska data

Godkännanden

Godkännanden



ROHS

Uppfyllelse

Downloads

Användardokumentation

[MAN IE GUIDE DE](#)
[MAN IE GUIDE EN](#)

Teknikuppgifter Data

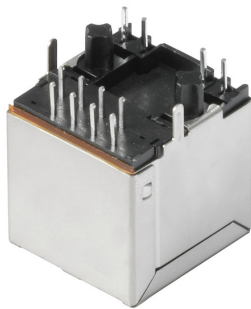
[STEP](#)

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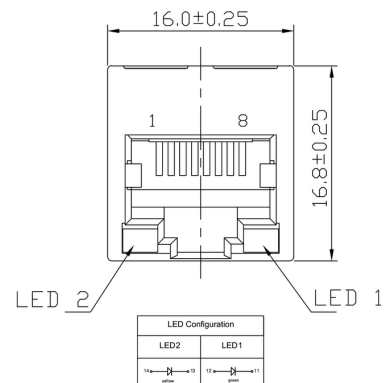
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Ritningar

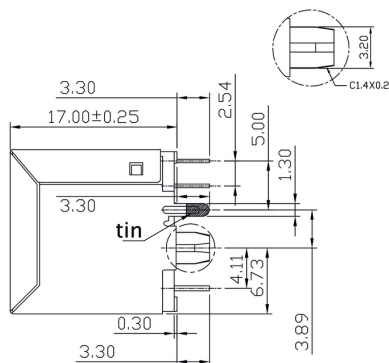
Profilritning



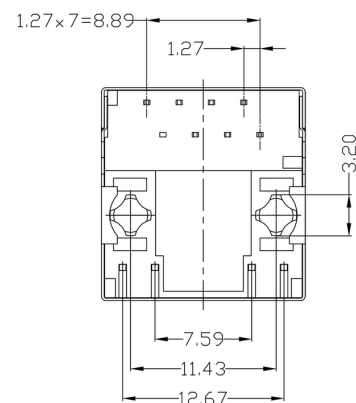
Dimensional drawing



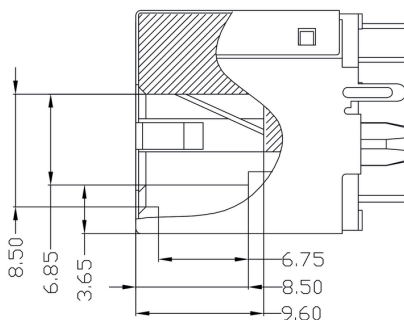
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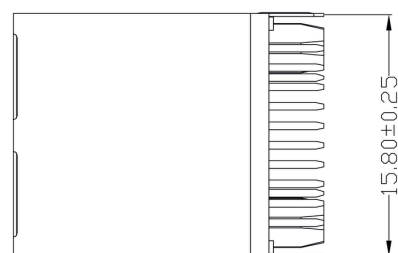
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Dimensional drawing



Dimensional drawing

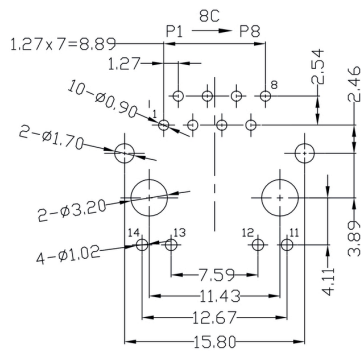


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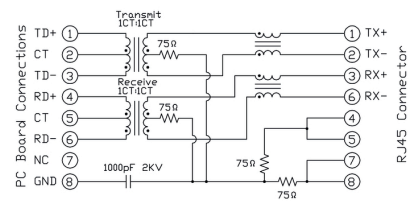
Ritningar

Kretskortsdesign



PCB LAYOUT

Kopplingsbild



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Ritningar

Schematic

Characteristics

Inductance	350 µH min. @ 100 kHz, 100 mV, 8 mA DC Bias
Leakage Inductance	0.3 µH max. @ 100 kHz, 100 mV
Insertion Loss	1.1 dB max. @ (1 - 100) MHz
Return Loss	18 dB min. @ (1 - 30) MHz 16 dB min. @ (30 - 60) MHz 12 dB min. @ (60 - 80) MHz
Cross Talk	30 dB min. @ (1 - 100) MHz
Common Mode Rejection	30 dB min. @ (1 - 100) MHz

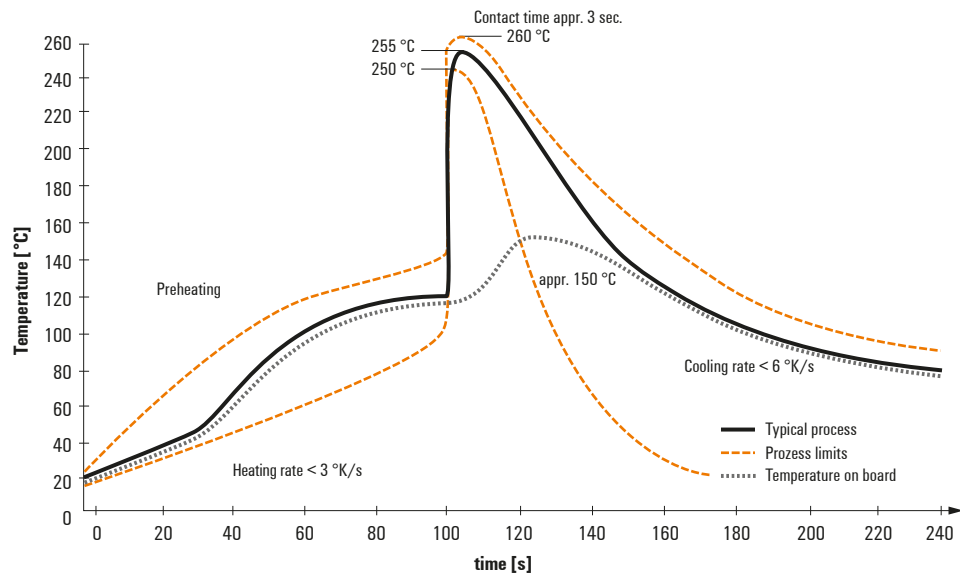
Type codes

RJ45	G1	R	1	U	3.2	E	4	GY/GY	TY	RJ45G1 R1U 3.2E4GY/GY TY																																																																																																																		
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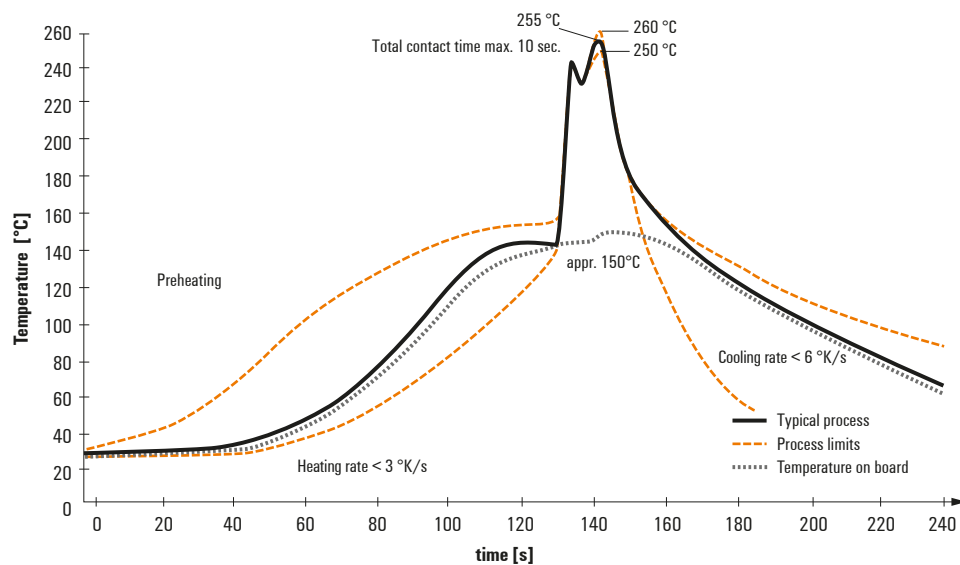
Recommended wave soldering profiles

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Germany
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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Germany
Fon: +49 5231 14-0
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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.